

General Information

Series Style

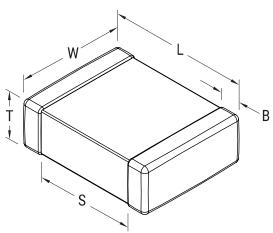


SMD Comm X8G HT150C Flex, Ceramic, 560 pF, 20%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206, 1.5 mm

SMD Comm X8G HT150C Flex

SMD Chip





T	B	Description	SMD, MLCC, High Temperature, Ultra-Stable
		Features	High Temperature, Ultra-Stable
		RoHS	Yes
		Termination	Flexible Termination
		Marking	No
S		AEC-Q200	No
		Typical Component Weight	15 mg
	Click here for the 3D model.	Shelf Life	78 Weeks
		MSL	1
Dimensions		Specifications	
Chin Sizo	1206	Capacitance	560 pF

Dimensions				
Chip Size	1206			
L	3.3mm +/-0.4mm			
W	1.6mm +/-0.35mm			
T	0.78mm +/-0.20mm			
S	1.5mm MIN			
В	0.6mm +/-0.25mm			

Packaging Specifications		
Packaging	T&R, 330mm, Plastic Tape	
Packaging Quantity	10000	

Specifications				
Capacitance	560 pF			
Measurement Condition	1 MHz 1.0Vrms			
Tolerance	20%			
Voltage DC	250 VDC			
Dielectric Withstanding Voltage	625 VDC			
Temperature Range	-55/+150°C			
Temp. Coefficient	X8G			
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms			
Dissipation Factor	0.1% 1 MHz 1.0Vrms			
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours			
Insulation Resistance	100 GOhms			

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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